

Name: Mini-Heizplattform

Modell: VB-215A

Temp. Bereich: 160~250°C

N.W.: 90,4g

Arbeitsbereich: 20 * 18,5 mm

Produktgröße: 70,5 x 76,7 x 21,6 mm

Anwendung: Geeignet für 99 % der Chips auf dem Markt, universell zum Entfernen von Kleber und Zinn von verschiedenen Arten von iPhones, Huawei und anderen Mobiltelefon-CPUs

Type-C USB

Mini Heating Platform

160°C~250°C Adjustable

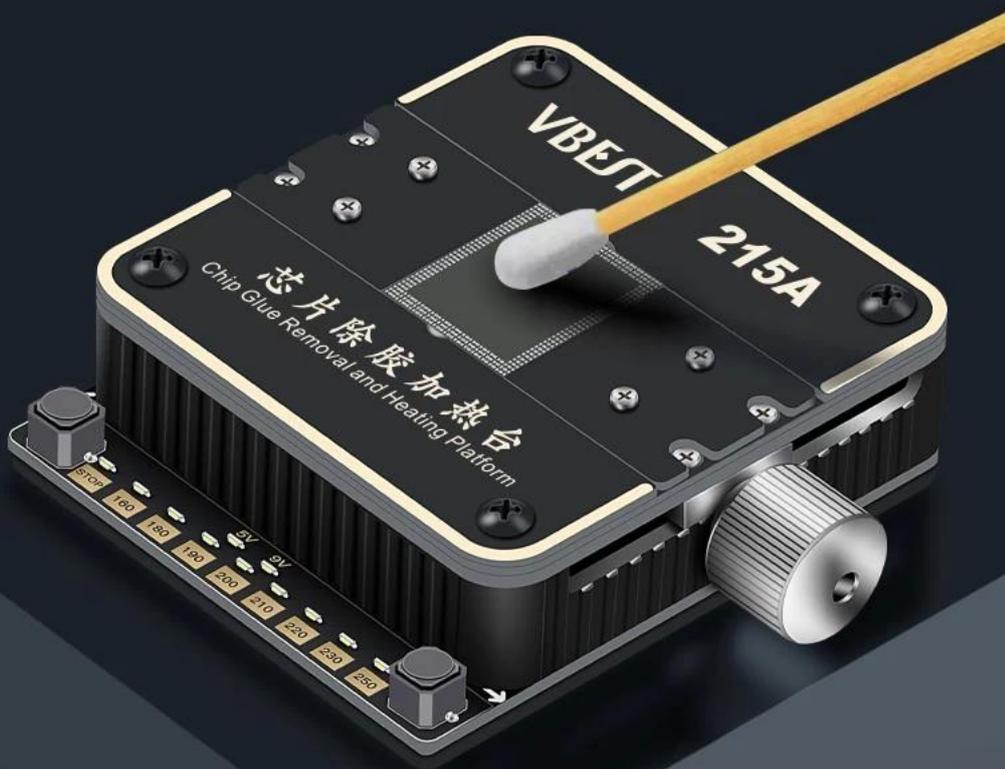
No need for heat gun or soldering iron heating, no need for soldering wick
No damage to solder pads and paint



No need for Soldering Wick



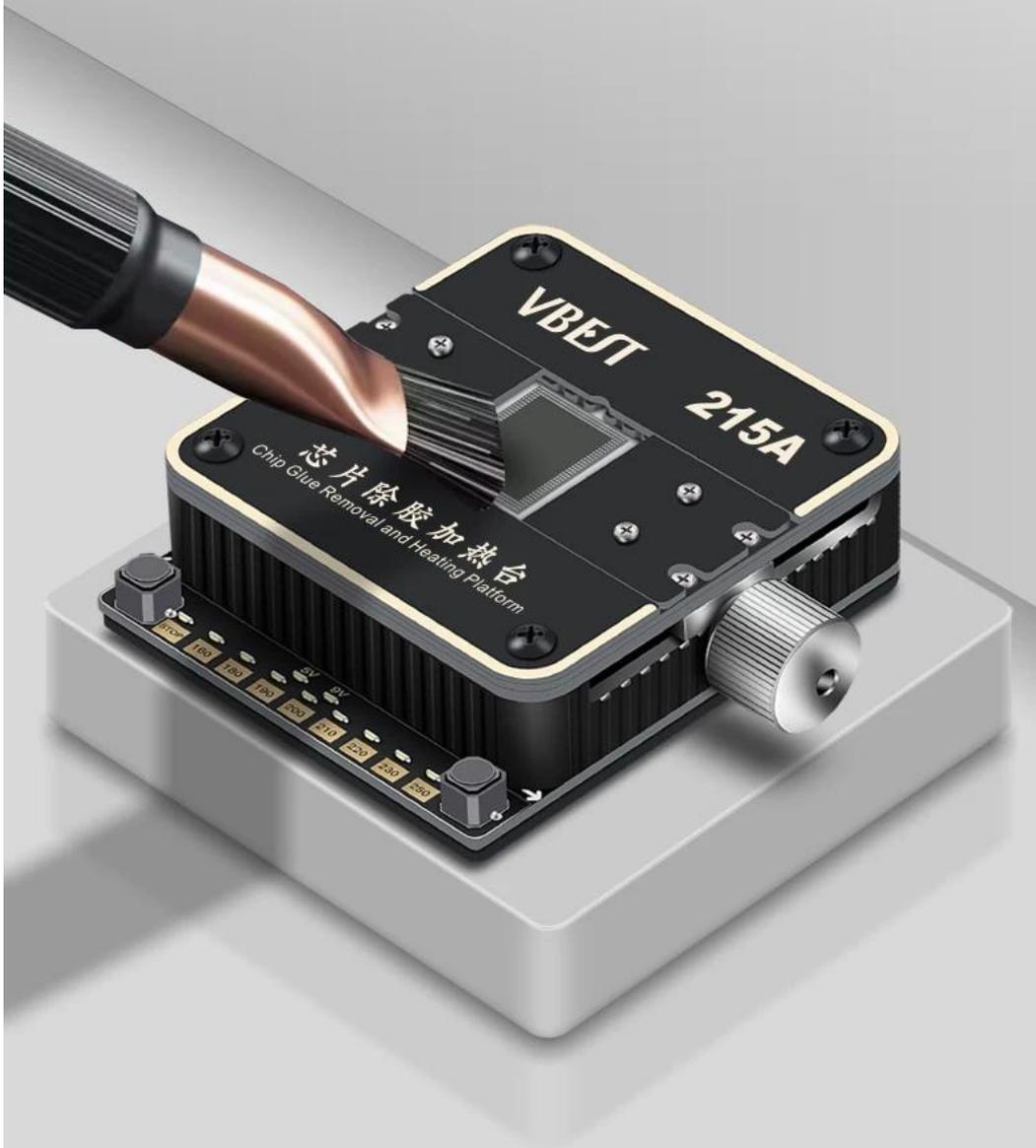
After heating to the set temperature, use a cotton swab to clean up the residual tin. No damage to the solder pad paint, no need for soldering wick wiping to wear out the chip



Heating to remove tin



Turn on the heating platform and heating to the preset temperature, you can use a brush or cotton swab to remove residual tin without soldering wick. Gently wipe to remove tin and glue easily.



160°C~250°C

Constant Temperature Heating



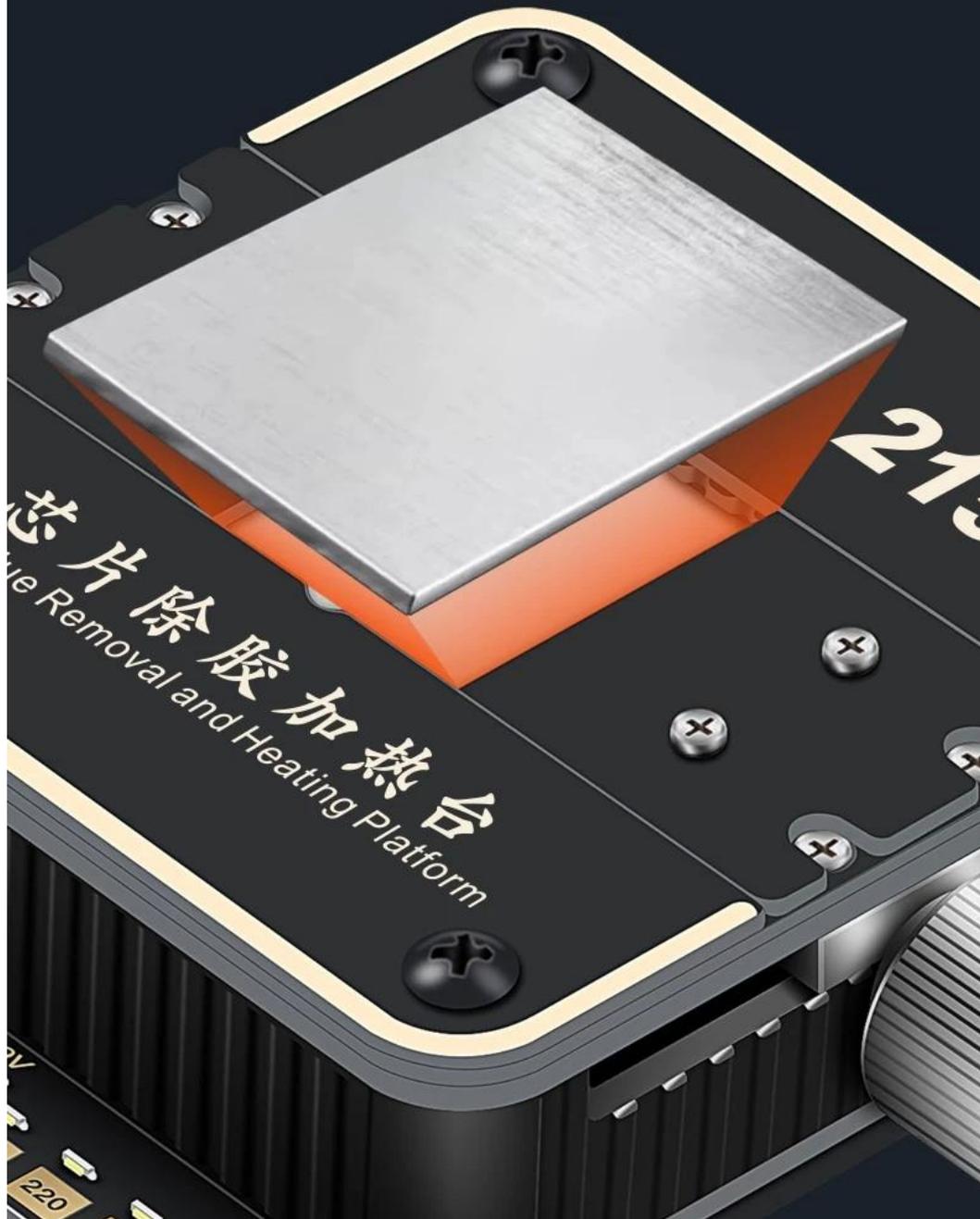
During heating operation, the temperature can be adjusted between 160~250 °C
Effectively prevent chip burnout caused by high temperature or improper adjustment



Low Voltage Heating Plate



Fast heating, no leakage, anti-static, safer heating
Built in professional tuning curve, no need to worry about
chip damage caused by thermal stress



Flexible hidden screw rod



Hidden screw rod, flexible and clever, extendable
and fixed clamping the chips
Prevent residue from falling into the screw,
making it more durable



Uniform Heating



No need for heat gun heating, it is safer to scrape glue
at a temperature 100 °C lower than the heat gun

No need to repeatedly scrape with a soldering iron,
no damage to the solder pads



Temperature adjustable

160~250°C

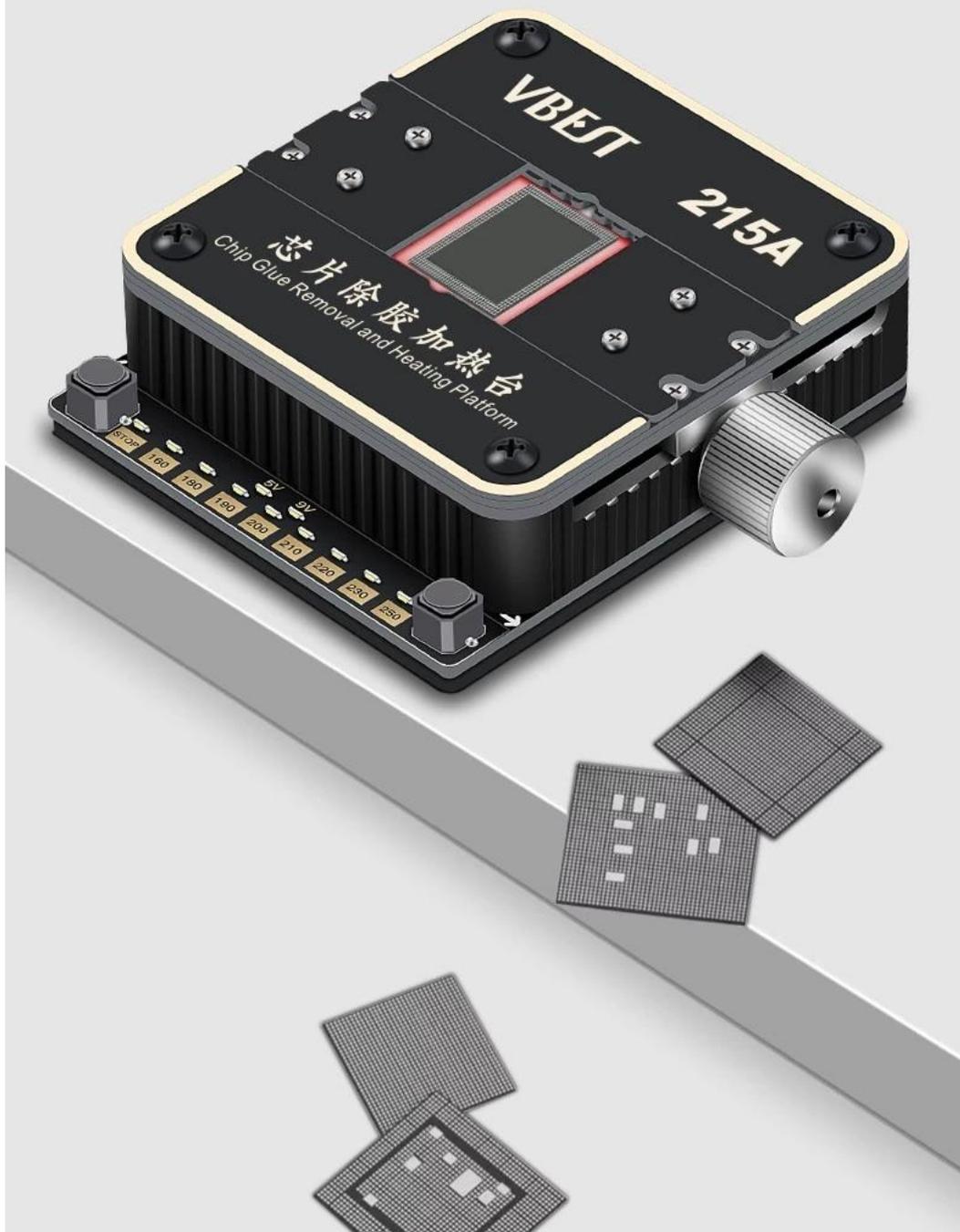


Suitable for 99% of chips

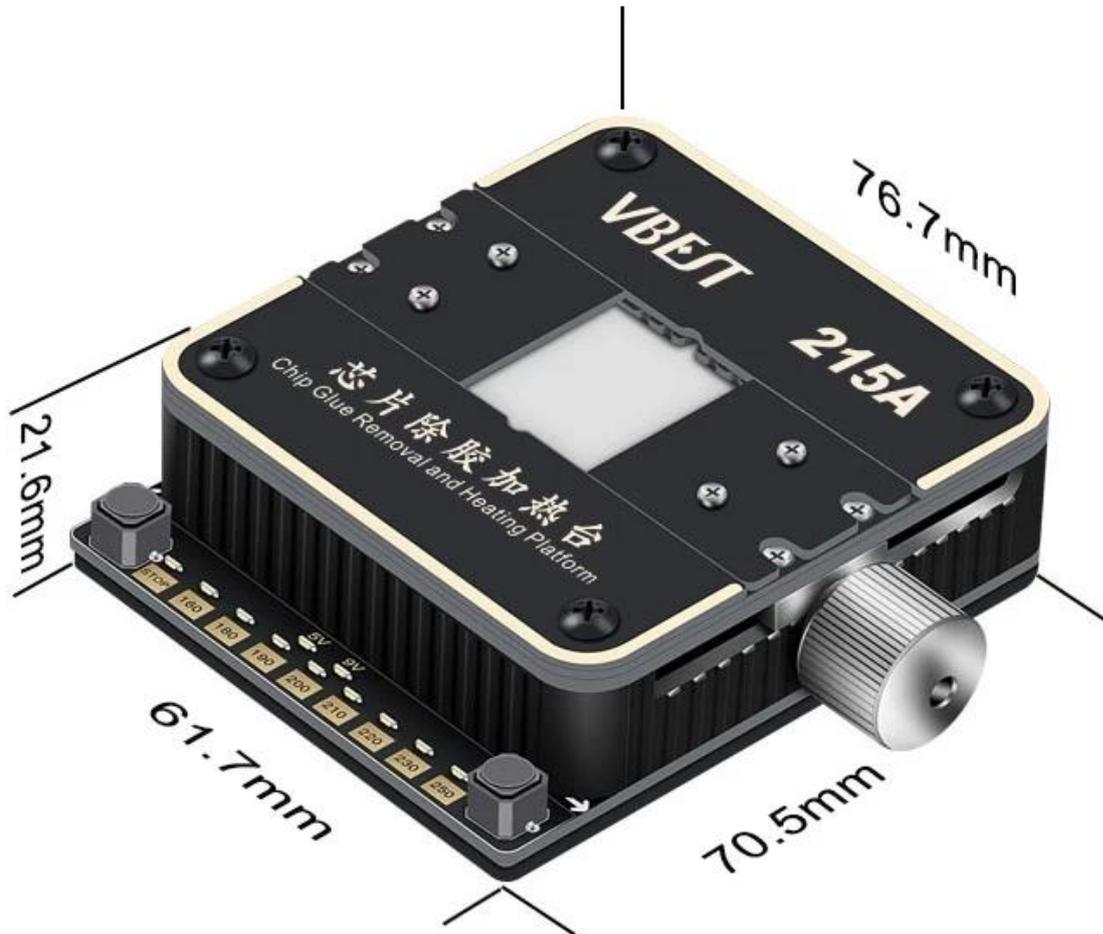


Work area: 20mm×18.5mm (Max)

Support multi generation iPh, Huawei phone CPU chips
and hard drives



Parameter



Name

Mini Heating Platform

Model

VB-215A

Temp. Range

160~250°C

N. W.

90.4g

Work area

20×18.5mm

Product Size

70.5×76.7×21.6mm

Application

Suitable for 99% of chips on the market, universal for removing glue and tin from various types of iPhones, Huawei and other mobile phone CPU

* The above dimensions are measured manually and may have about 1-2mm error